

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT3793386

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	SII CRYSTAL TECHNOLOGY INC.	02/26/2016
RECEIVING PARTY DATA		
Name:	SEIKO INSTRUMENTS INC.	
Street Address:	8, NAKASE 1-CHOME, MIHAMA-KU	
City:	CHIBA-SHI, CHIBA	
State/Country:	JAPAN	
Postal Code:	261-8507	
PROPERTY NUMBERS Total: 4		
Property Type	Number	
Application Number:	12759417	
Application Number:	13114415	
Application Number:	13163096	
Application Number:	13177898	
CORRESPONDENCE DATA		
Fax Number:	(312)321-4299	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	312-321-4200	
Email:	khinokawa@brinksgilson.com, usassignments@brinksgilson.com	
Correspondent Name:	TADASHI HORIE/KOH HINOKAWA	
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ATTORNEY DOCKET NUMBER:	11106/302,/449,/454,/460	
NAME OF SUBMITTER:	TADASHI HORIE	
SIGNATURE:	/Tadashi Horie/	
DATE SIGNED:	03/21/2016	
Total Attachments: 4		
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PATENT ASSIGNMENT AGREEMENT

This PATENT ASSIGNMENT AGREEMENT (this "Assignment") is entered into by and between SII Crystal Technology Inc., a corporation organized and existing under the laws of Japan, having a place of business at 8, Nakase 1-chome, Mihama-ku, Chiba-shi, Chiba, Japan 261-8507, ("Assignor") and Seiko Instruments Inc., a corporation organized and existing under the laws of Japan, having a place of business at 8, Nakase 1-chome, Mihama-ku, Chiba-shi, Chiba, Japan 261-8507, ("Assignee"), and (each, a "party," and collectively, the "parties").

WHEREAS, Assignor has agreed to assign to Assignee, and Assignee desires to receive from Assignor, all of Assignor's right, title and interest in and to the patents and patent applications identified on Schedule A attached hereto (the "Patents"),.

NOW, THEREFORE, in consideration of the premises and the mutual agreements and covenants hereinafter set forth, the parties hereto agree as follows:

1. Assignment (a) Assignor hereby irrevocably assigns, transfers, conveys and delivers to Assignee, free and clear of any Encumbrances (other than Permitted Encumbrances), and Assignee hereby receives from Assignor, all of Assignor's right, title and interest in and to the Patents for the United States and for all foreign countries, including, without limitation, the inventions and improvements described and claimed therein, all reissuances, revisions, divisionals, continuations, extensions, continuations-in-part and counterparts thereof and all corresponding rights that are or may be secured under the laws of the United States or any foreign country, now or hereafter arising or in effect, for Assignee's own use and enjoyment, and for the use and enjoyment of Assignee's successors, assigns and other legal representatives, as fully and entirely as the same would have been held and

enjoyed by Assignor if this Assignment had not been made, together with all rights to collect royalties, products and proceeds in connection with any of the foregoing and all rights to sue and recover damages or other relief for all past, present or future infringement, misappropriation or other violation of any of the foregoing, and all rights corresponding thereto throughout the world.

(b) Assignor hereby requests the Commissioner of Patents and Trademarks in the United States Patent and Trademark Office, and the corresponding entities or agencies in any applicable foreign countries or multinational authorities, to record Assignee as the assignee and owner of the Patents and to deliver to Assignee, and to Assignee's attorneys, agents, successors or assigns, all official documents and communications as may be warranted by this Assignment.


2. Further Action. Assignor and Assignee shall each take, and shall cause their respective Affiliates to take, any and all additional actions as may be necessary or appropriate to effect the transactions contemplated hereby, including, but not limited to, execution of individual assignment documentation for filing with the authorities of each individual country. The responsibility to file assignments with the national patent offices of each country shall be on the Assignee and the Assignee shall bear the cost of filing such assignments.

3. Counterparts. This Assignment may be executed and delivered (including by facsimile or other means of electronic transmission, such as by electronic mail in "pdf" form) in one or more counterparts, and by the different parties hereto in separate counterparts, each of which when executed shall be deemed to be an original, but all of which taken together shall constitute one and the same agreement.

4. Governing Law. This Assignment shall be governed by, and construed in accordance with, the Laws of Japan.

IN WITNESS THEREOF, the parties hereto have caused this Assignment to be executed as of the date last written below by their respective officers thereunto duly authorized.

Seiko Instruments Inc.

By 

Name Toshihiko SAKUHARA

Title General Manager,

Intellectual Property Dept.

Date February 24, 2016

SII Crystal Technology Inc.

By 

Name Toru MATSUNO

Title President

Date Feb 26, 2016

Schedule A

Patent Number	Patent Issue Date	Application Number	Filing Date	Title	Client Reference Number	Attorney Docket Number
8,441,799	05-14-2013	12/759,417	04-13-2010	ELECTRONIC COMPONENT AND ELECTRONIC DEVICE	08P00804	11106/302
8,461,665	06-11-2013	13/114,415	05-24-2011	WAFER AND PACKAGE PRODUCT MANUFACTURING METHOD	08P00666	11106/449
8,540,550	09-24-2013	13/163,096	06-17-2011	GLASS SUBSTRATE POLISHING METHOD, PACKAGE MANUFACTURING METHOD, PIEZOELECTRIC VIBRATOR, OSCILLATOR, ELECTRONIC DEVICE AND RADIO TIMEPIECE	09P00030	11106/454
8,918,971	12-30-2014	13/177,898	07-07-2011	METHOD OF MANUFACTURING PACKAGES	08P00767	11106/460